

Electronic Patent Application Fee Transmittal				
Application Number:		10581165		
Filing Date:		31-May-2006		
Title of Invention:		Ultra-Low Dielectrics Film for Copper Interconnect		
First Named Inventor/Applicant Name:		Hee-Woo Rhee		
Filer:		Howard C. Lee/Jennifer Hardy		
Attorney Docket Number:		930086-2027		
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				310